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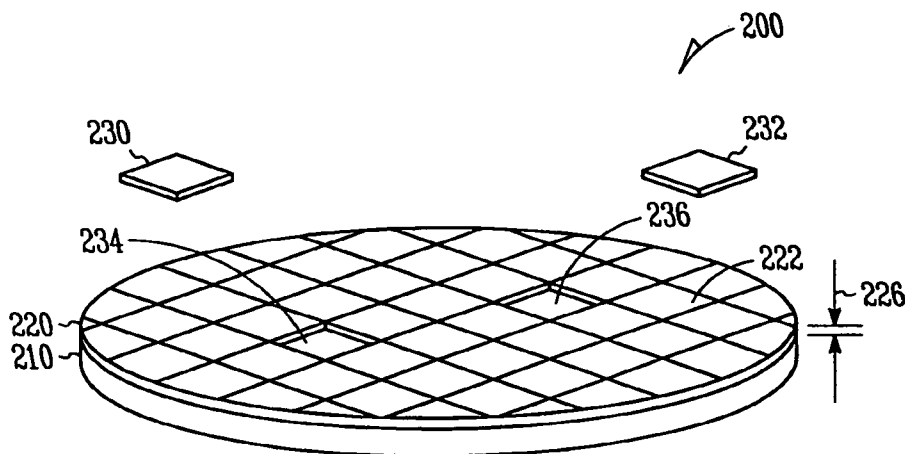
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(54) Title: METHOD OF MANUFACTURING STACKED CHIP PACKAGES



(57) Abstract: Methods and devices for multi-chip stacks are shown. A method is shown that assembles multiple chips into stacks by stacking wafers prior to dicing into individual chips. Methods shown provide removal of defective chips and their replacement during the assembly process to improve manufacturing yield.

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